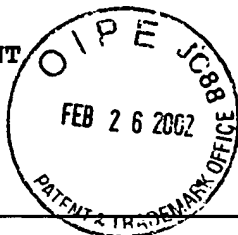


FORM PTO-1449

INFORMATION DISCLOSURE STATEMENT



ATTY DOCKET NO.

50439-2

SERIAL NO.

09/605,442

APPLICANT(S): Barstad et al.

FILING DATE:

June 28, 2000

ART UNIT:

1741

UNITED STATES PATENT DOCUMENTS

EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
WA.	AA	5,252,196	10/12/93	Sonnenberg et al.	/	/	/
	AB	3,770,598	11/06/73	Creutz	/	/	/
↓	AC	3,784,454	01/08/74	Lyde	/	/	/
WA.	AD	4,347,108	08/31/82	Willis	/	/	/

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRAN YES/NO

RECEIVED
MAR 04 2002
TC 1700

COPY OF PAPERS
ORIGINALLY FILED

OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)

Examiner:

Date:

8/27/02

Sheet 1 of 1

FORM PTO-1449				ATTY DOCKET NO.		SERIAL NO.	
INFORMATION DISCLOSURE STATEMENT				50439		09/313,045	
				APPLICANT(S): Barstad et al.			
				FILING DATE: May 17, 1999		ART UNIT: 1741	
UNITED STATES PATENT DOCUMENTS							
EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
	AA	3,876,513	04/08/75	Brown et al.			
	AB	4,098,656	07/04/78	Deubor			
	AC	4,530,741	07/23/85	Rosenberg			
	AD	4,913,787	04/03/90	Kiso			
	AE	5,051,154	09/24/91	Bernards et al.			
	AF	5,068,013	11/26/91	Bernards et al.			
	AG	5,174,886	12/29/92	King et al.			
	AH	5,223,118	06/29/93	Sonnenberg et al.			
	AJ	5,858,870	01/12/99	Zheng et al.			
	AK	5,433,840	07/95	Dahms et al.			
	AL	2,424,887	07/47	Henricks			
	AM	5,151,170	09/92	Montgomery et al.			
	AN	4,347,108	08/82	Willis			
	AO	4,336,114	06/82	Mayer et al.			
	AP	4,036,710	07/77	Kardos et al.			
	AQ	5,113,771	09/00	Landau et al.			
	AR	5,068,013	11/91	Bernards et al.			
	AS	5,051,154	09/91	Bernards et al.			
	AT	6,024,857	02/00	Reid			
OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)							
	BA	Shipley Advance Interconnect, Advanced Interconnect Materials, "Nanoplate™ Copper Plating Electrolyte Optimized for 200 nm, Bottom-up Trench Fill" Shipley Company, L.L.C. data sheet.					
Examiner:							
Date:							